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(71) Applicant: **AZ ELECTRONIC MATERIALS (LUX-EMBOURG) S.A.R.L.** [LU/LU]; 46 Place Guillaume II, 1648 Luxembourg (LU).

(72) Inventors: **YAMAMOTO, Kazuma**; c/o Merck Performance Materials Ltd., 3330, Chihama, Kakegawa-shi, Shizuoka 437-1412 (JP). **ISHII, Maki**; c/o Merck Performance Materials Ltd., 3330, Chihama, Kakegawa-shi, Shizuoka 437-1412 (JP). **YASHIMA, Tomoyasu**; c/o Merck Performance Materials Ltd., 3330, Chihama, Kakegawa-shi, Shizuoka 437-1412 (JP). **NAGAHARA, Tatsuro**; c/o Merck Performance Materials Ltd., 3330, Chihama, Kakegawa-shi, Shizuoka 437-1412 (JP).

(74) Agent: **B2B PATENTS**; c/o Merck Patent GmbH, 64271 Darmstadt (DE).

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(54) Title: A LITHOGRAPHY COMPOSITION, A METHOD FOR FORMING RESIST PATTERNS AND A METHOD FOR MAKING SEMICONDUCTOR DEVICES

(57) Abstract: The present invention relates to a new lithography composition, the forming of resist patterns using the lithography composition, and a semiconductor device manufacturing method using the lithography composition in a photolithography method.

WO 2018/095885 A1